

Product End-of-Life Disassembly Instructions

Product Category: Servers
Marketing Name / Model
HPE ProLiant Compute DL360 Gen12

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by Directive 2012/19/EU of the European Parliament and of the Council on Waste Electrical and Electronic Equipment (WEEE). Detailed removal instructions are available in the server Maintenance and Service Guide on the [HPE Product Support Center](#).

1.0 Items Requiring Selective Treatment

- 1.1 The items listed below are classified as requiring selective treatment.
- 1.2 Quantities vary by product configuration

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	9
Batteries	All types including standard alkaline and lithium coin or button style batteries	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	Quantity varies by product configuration and power supply model selected	Up to 10
External electrical cables and cords	Quantity depends on number of power supplies, networking devices, and I/O devices	Up to 2
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		

Item Description	Notes	Quantity of items included in product
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx driver	T10/T15
Phillips screwdriver	#2
Flathead screwdriver	Medium

3.0 Product Disassembly Process

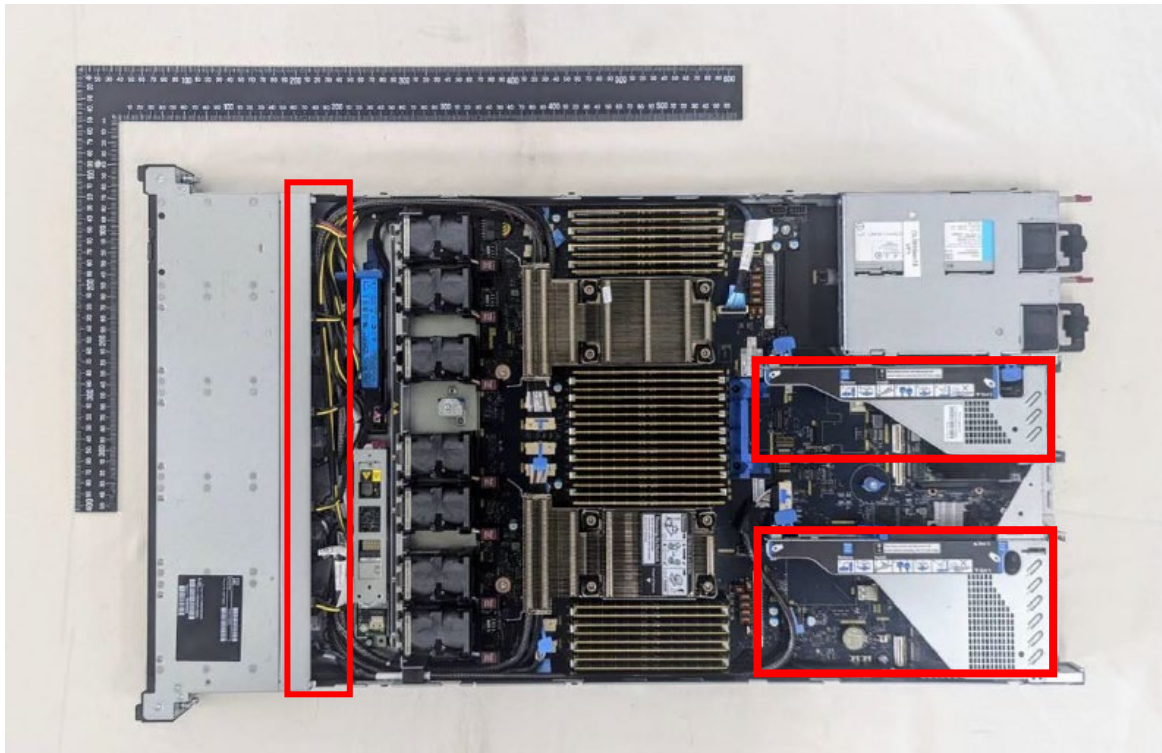
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment. Provide links to the product Maintenance and Service Guide where reference is needed for detailed disassembly instructions.

1. Remove the Controller (PCBA) by Torx Driver and dispose properly.
2. Remove the Shiner Card (PCBA) by Torx Driver and dispose properly.
3. Remove Backplane (PCBA) by Torx Driver and dispose properly.
4. Remove the top cover and locate the Lithium battery on the system board. Remove the Lithium battery with medium flat head screwdriver and dispose of properly.
5. Remove the top cover and locate the megacell on the system board. Remove the megacell with a medium-flat head screwdriver and dispose of it properly.
6. Remove the Capacitors > 2.5CM of the power supply(s) from the system. Remove the screws by #2 Philips screwdriver, securing the top cover and the heatsinks in the P/S, then locate the capacitors and pry from the PCB with a medium flat head screwdriver.

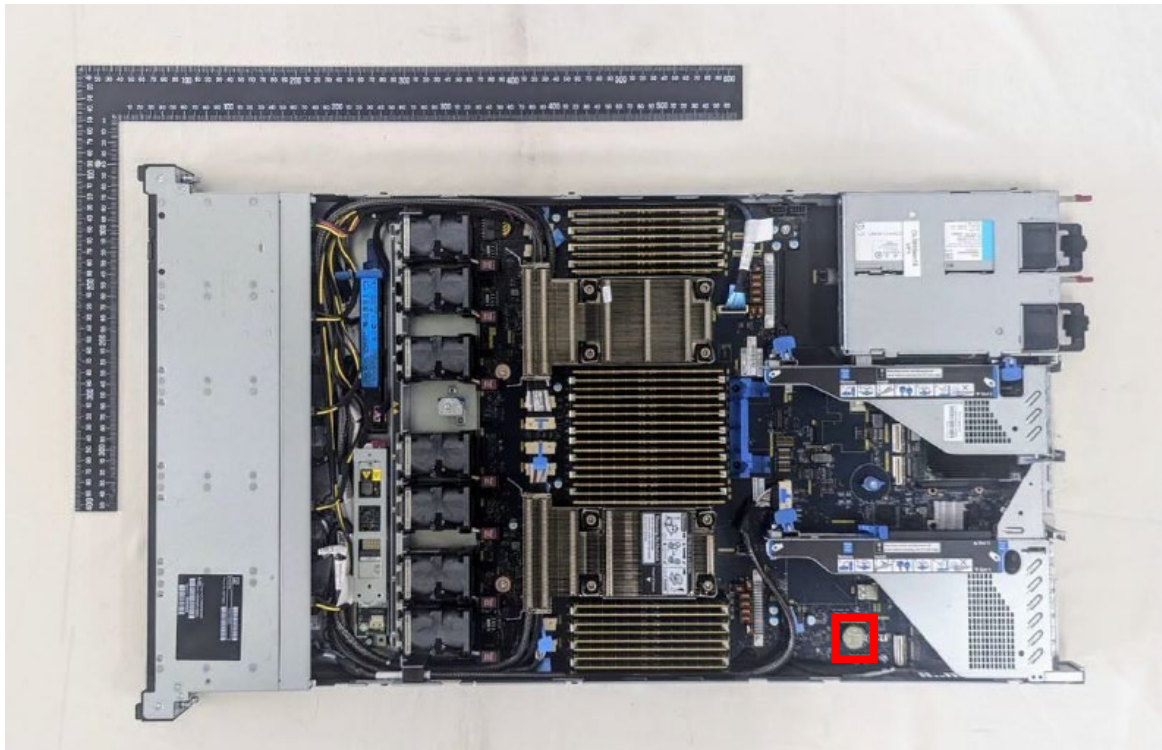
For detailed removal instructions, see the product Maintenance and Service Guide [here](#).

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

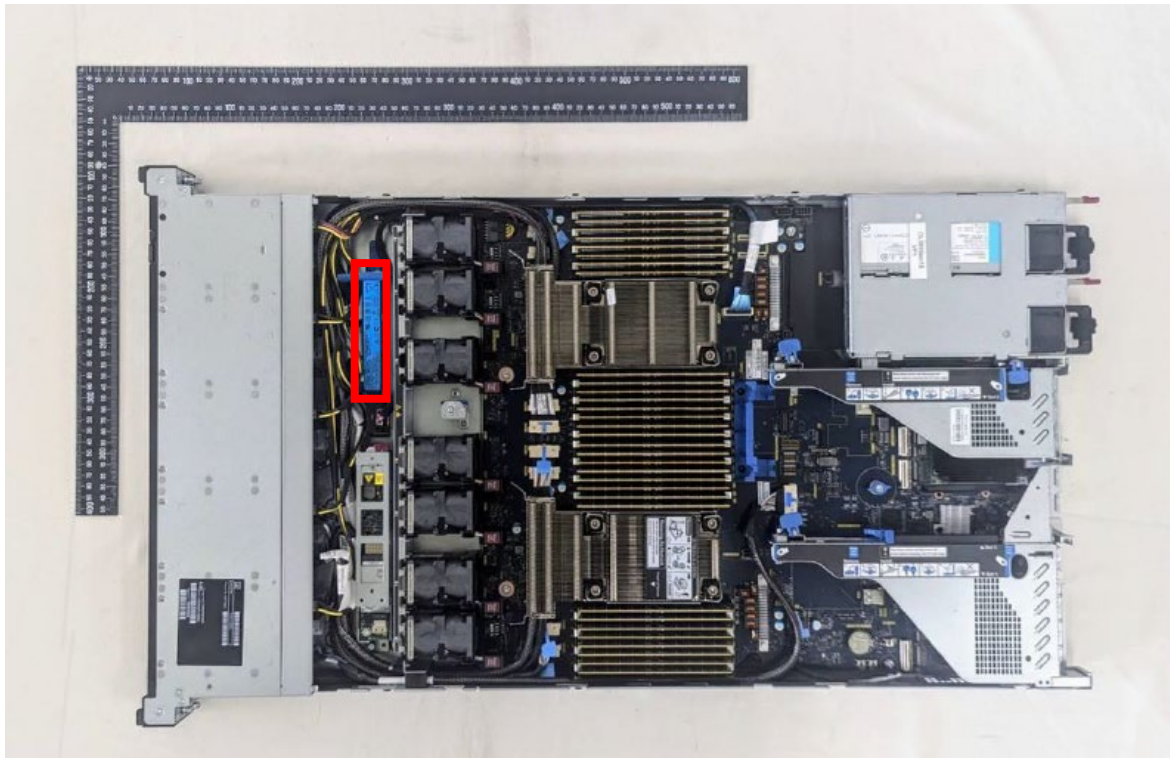
Attachment 1: Remove shiner card and Backplane PCBA.



Attachment 2: Remove lithium battery



Attachment 3 : Remove mega-cell HSTNS-BB05



Attachment 4: Remove Electrolytic Capacitor (C801:25mm*60mm and C237/C238/C241:10mm*25) from power supply HSTNS-PD41-1.



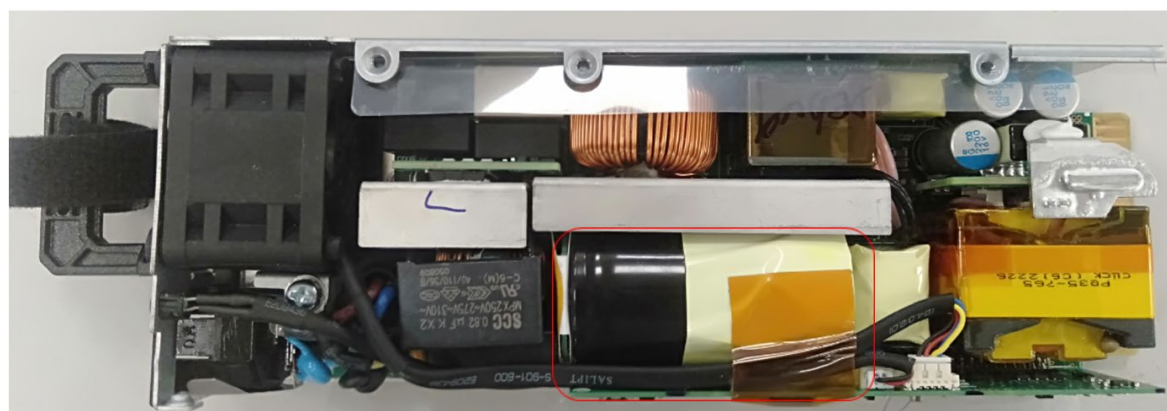
Attachment 5: Remove Electrolytic Capacitor (BC1: 25mm*60 mm and C106/C107/C108 10mm*25mm) from power supply HSTNS-PC41-1



Attachment 6: Remove Electrolytic Capacitor (C102: 30mm*30mm) from power supply HSTNS-PL41-1.

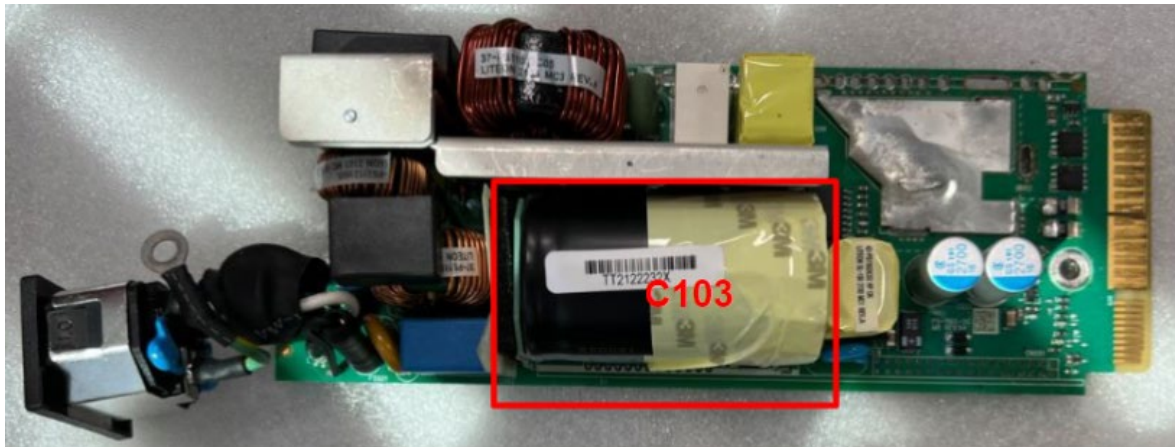


Attachment 7: Remove Electrolytic Capacitor (C103: 230mm*50 mm) from power supply HSTNS-PD67.

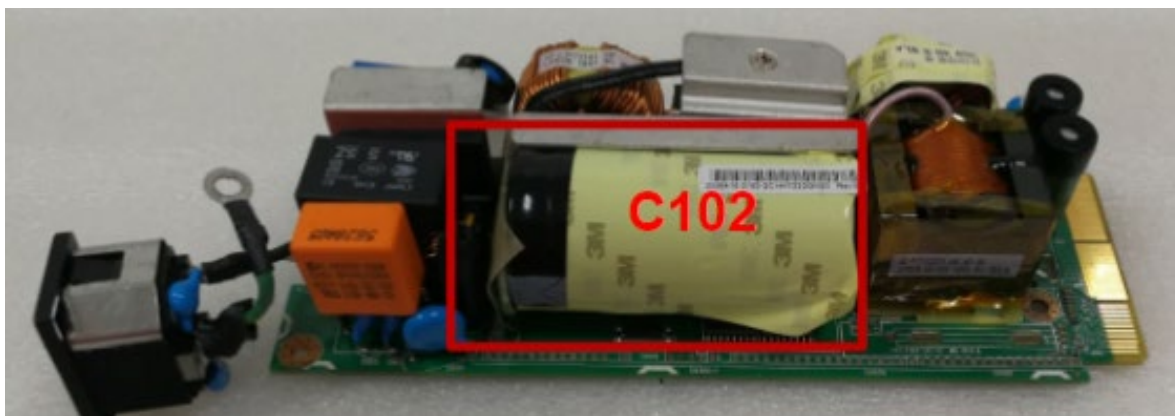


C103

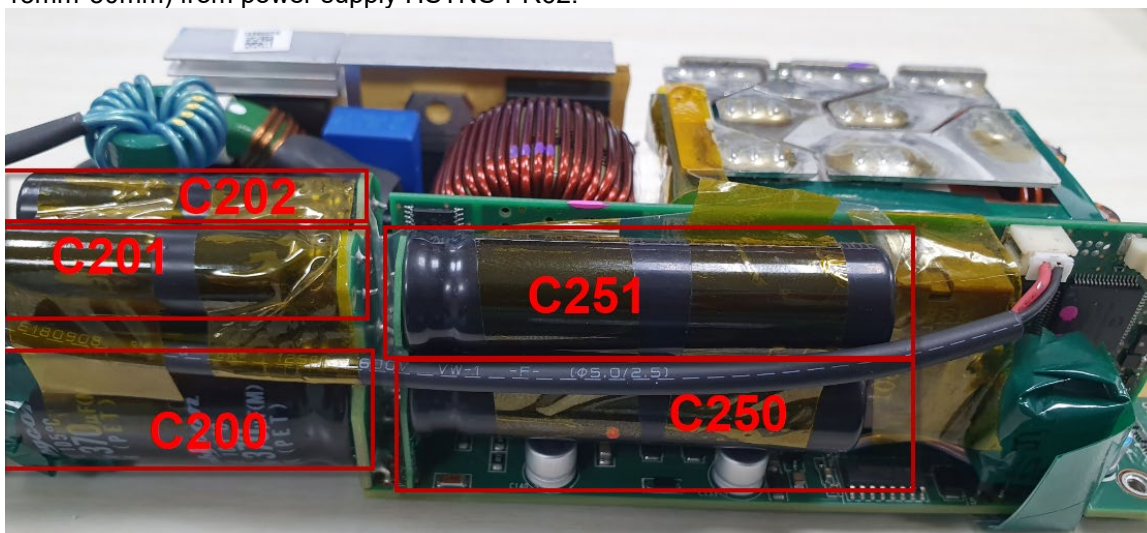
Attachment 8: Remove Electrolytic Capacitor (C103: 30mm*50 mm) from power supply HSTNS-PL67.



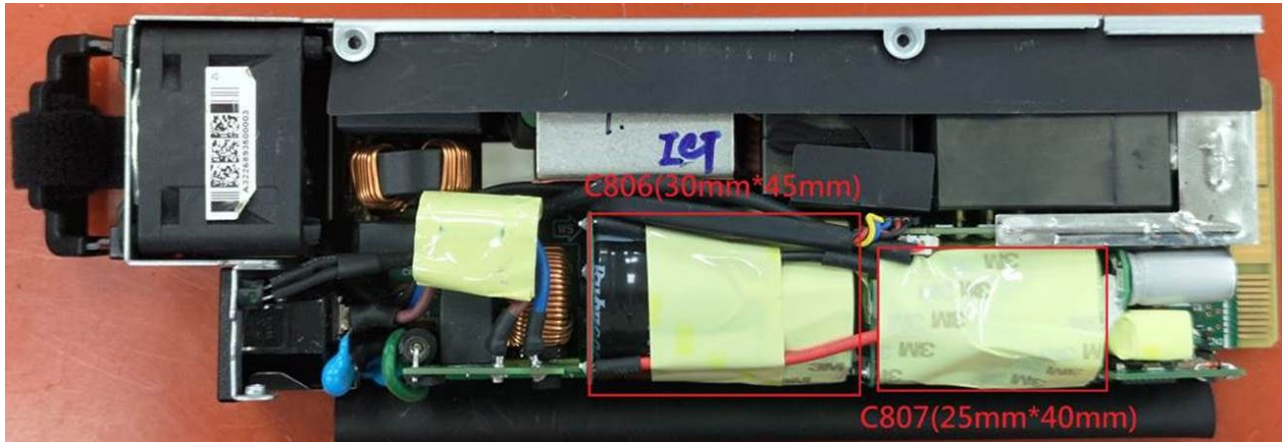
Attachment 9: Remove Electrolytic Capacitor (C102: 30mm*60mm) from power supply HSTNS-PL62.



Attachment 10: Remove Electrolytic Capacitors (C201,202: 10mm*38.5mm, C200: 26mm*43mm , C250,251: 13mm*50mm) from power supply HSTNS-PR62.



Attachment 11: Remove Electrolytic Capacitor (C806: 30mm*45mm and C807: 25mm*40mm) from power supply HSTNS-PD72.



Attachment 12: Remove Electrolytic Capacitor (C101: 30mm*70mm and C925:10mm*25mm) from power supply HSTNS-PL72.

